



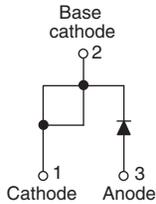
## Ultralow $V_F$ Hyperfast Rectifier for Discontinuous Mode PFC, 8 A FRED Pt®



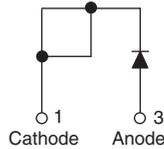
TO-220AC



TO-220 FULL-PAK



VS-8ETL06PbF  
VS-8ETL06-N3



VS-8ETL06FPPbF  
VS-8ETL06FP-N3

### FEATURES

- Hyperfast recovery time
- Benchmark ultralow forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Fully isolated package ( $V_{INS} = 2500 V_{RMS}$ )
- UL E78996 pending
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### DESCRIPTION

State of the art, ultralow  $V_F$ , soft-switching hyperfast rectifiers optimized for Discontinuous (Critical) Mode (DCM) Power Factor Correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

### APPLICATIONS

AC/DC SMPS 70 W to 400 W  
e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units and DVD AC/DC power supplies.

PRODUCT SUMMARY	
Package	TO-220AC, TO-220FP
$I_{F(AV)}$	8 A
$V_R$	600 V
$V_F$ at $I_F$	0.81 V
$t_{rr}$ typ.	60 ns
$T_J$ max.	175 °C
Diode variation	Single die

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Repetitive peak reverse voltage	$V_{RRM}$		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 160\text{ °C}$	8	A
		$T_C = 142\text{ °C}$		
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$	175	
Repetitive peak forward current	$I_{FM}$		16	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-65 to +175	°C

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\ \mu A$	600	-	-	V
Forward voltage	$V_F$	$I_F = 8\text{ A}$	-	0.96	1.05	
		$I_F = 8\text{ A}, T_J = 150\text{ °C}$	-	0.81	0.86	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	0.05	5	$\mu A$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	20	100	
Junction capacitance	$C_T$	$V_R = 600\text{ V}$	-	17	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	60	100	ns
		$I_F = 8\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	150	250	
		$T_J = 25\text{ }^\circ\text{C}$	-	170	-	
		$T_J = 125\text{ }^\circ\text{C}$	-	250	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	-	15	-	A
		$T_J = 125\text{ }^\circ\text{C}$	-	20	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	-	1.3	-	$\mu\text{C}$
		$T_J = 125\text{ }^\circ\text{C}$	-	2.6	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-65	-	175	$^\circ\text{C}$
Thermal resistance, junction to case (FULL-PAK)	$R_{thJC}$		-	1.4	2	$^\circ\text{C}/\text{W}$
			-	3.4	4.3	
Thermal resistance, junction to ambient per leg	$R_{thJA}$	Typical socket mount	-	-	70	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth and greased	-	0.5	-	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-220AC	8ETL06			
		Case style TO-220 FULL-PAK	8ETL06FP			

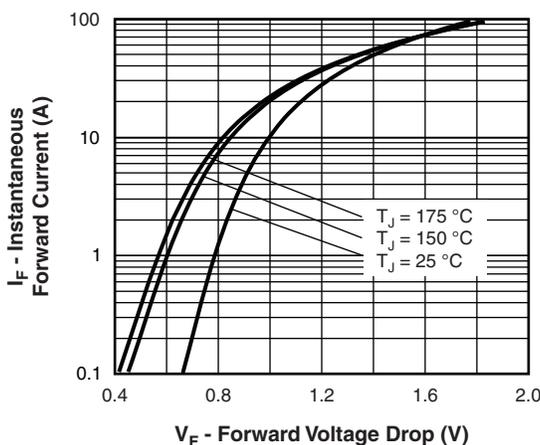


Fig. 1 - Typical Forward Voltage Drop Characteristics

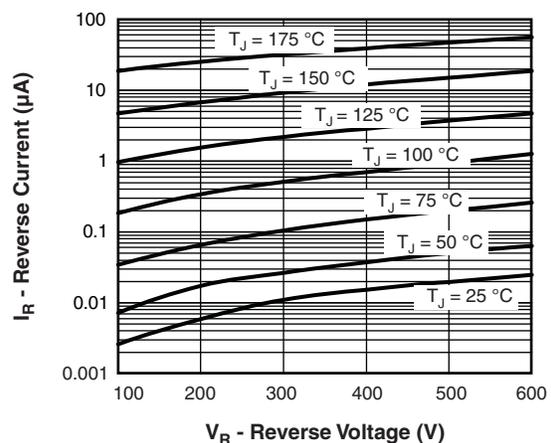


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

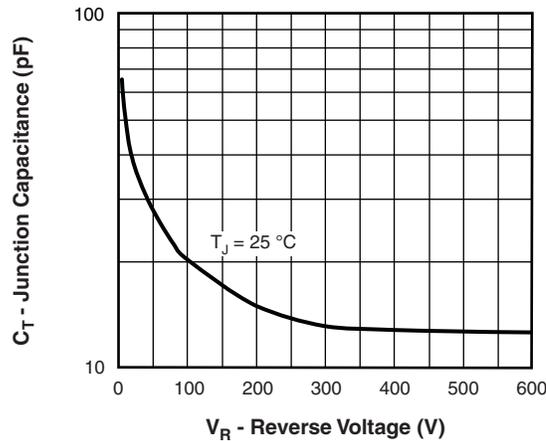


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

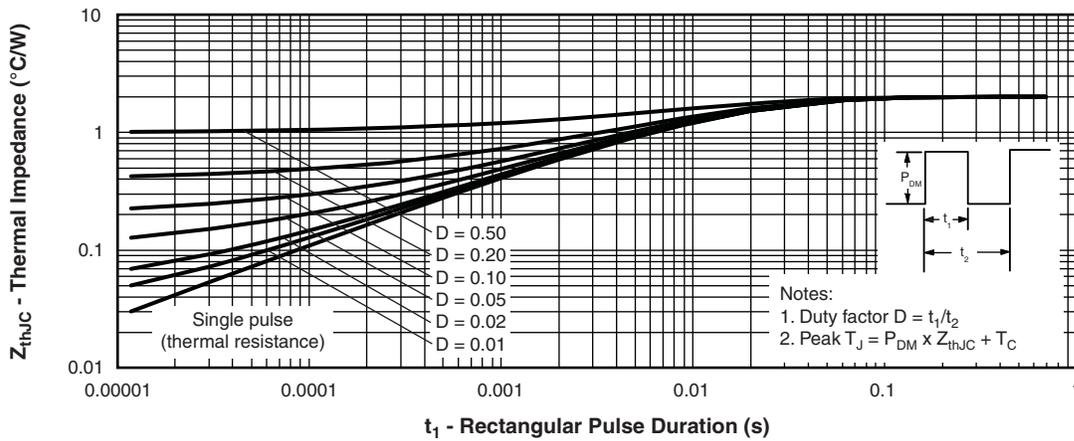


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

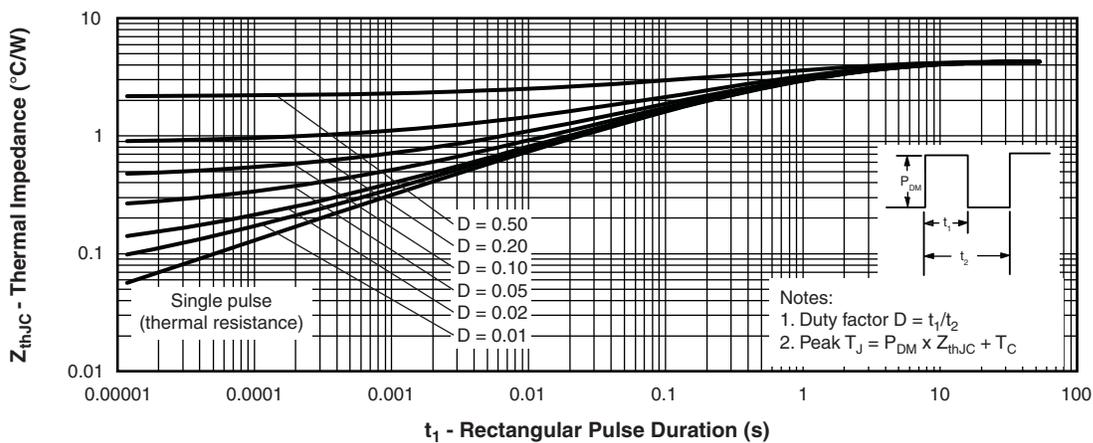


Fig. 5 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (FULL-PAK)

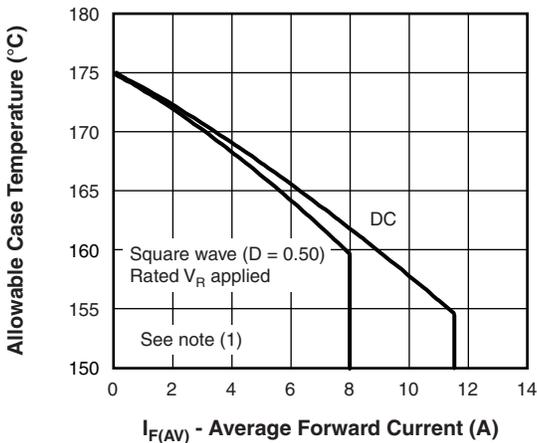


Fig. 6 - Maximum Allowable Case Temperature vs. Average Forward Current

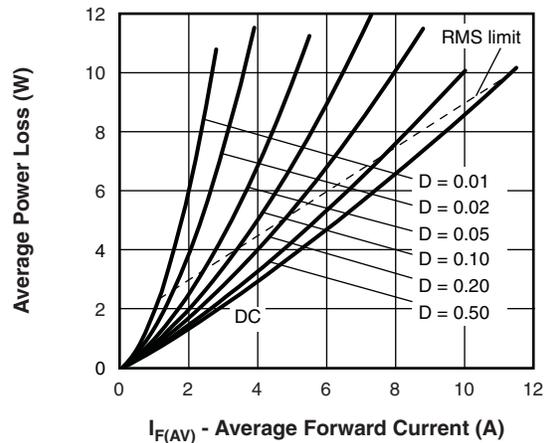


Fig. 8 - Forward Power Loss Characteristics

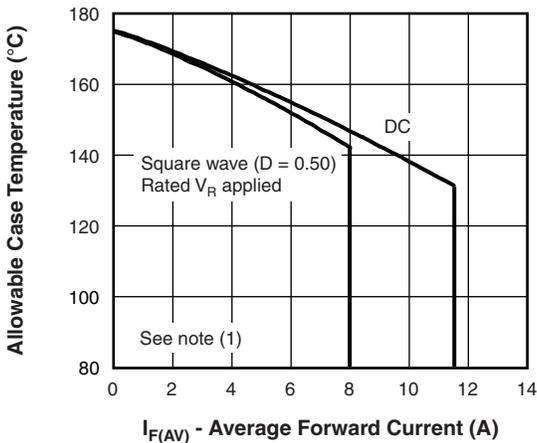


Fig. 7 - Maximum Allowable Case Temperature vs. Average Forward Current (FULL-PAK)

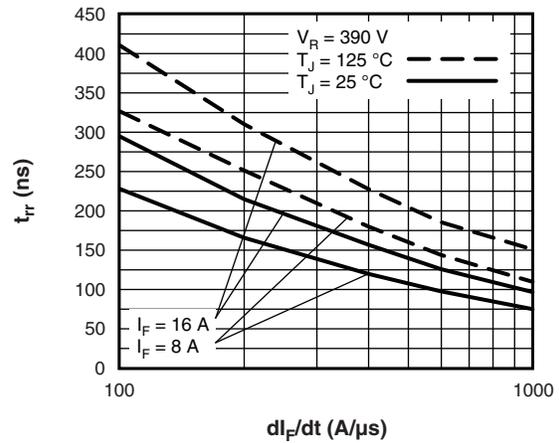


Fig. 9 - Typical Reverse Recovery Time vs.  $dI_F/dt$

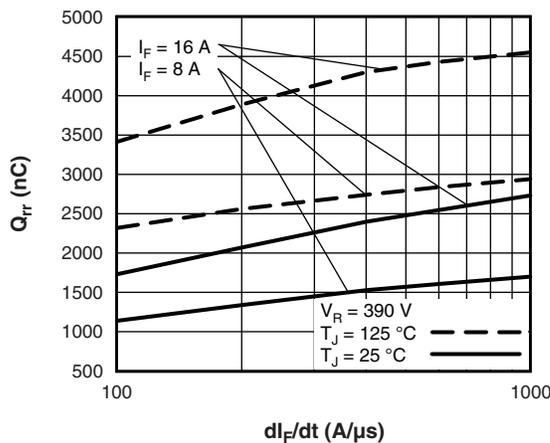


Fig. 10 - Typical Stored Charge vs.  $dI_F/dt$

**Note**

(1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = Forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 8);  $P_{dREV}$  = Inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = Rated  $V_R$

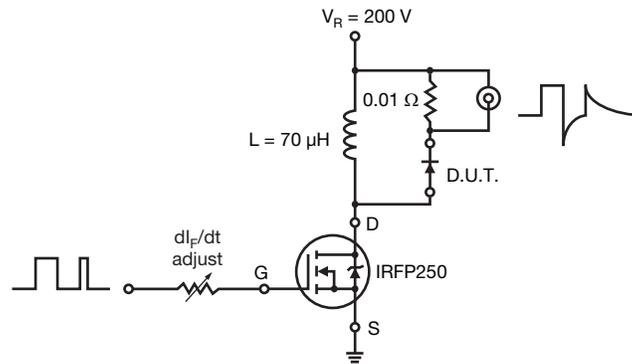
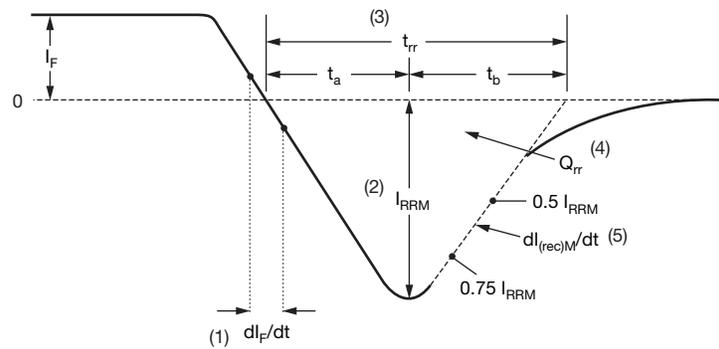


Fig. 11 - Reverse Recovery Parameter Test Circuit

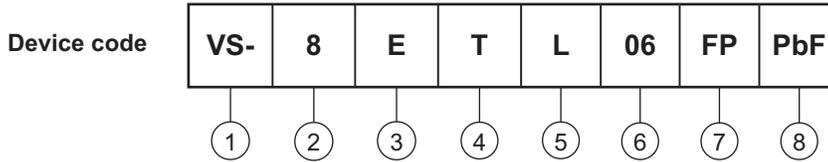


- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- $$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$
- (5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

Fig. 12 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



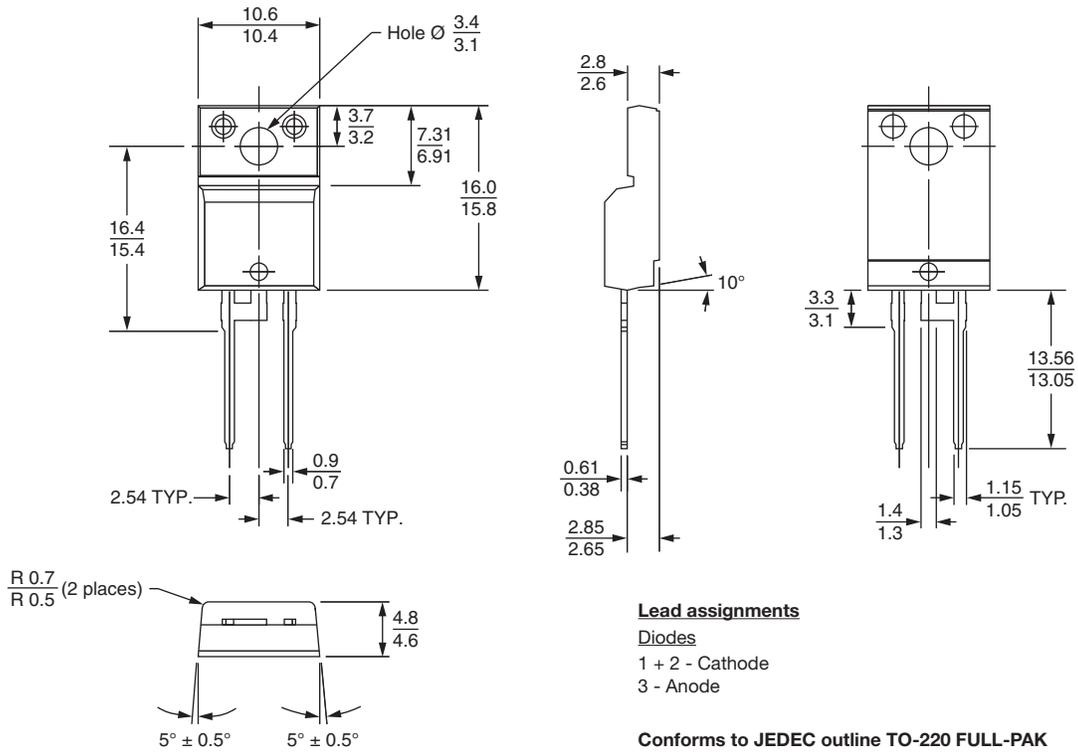
- ① - Vishay Semiconductors product
- ② - Current rating (8 = 8 A)
- ③ - E = single diode
- ④ - T = TO-220, D<sup>2</sup>PAK
- ⑤ - L = ultralow V<sub>F</sub> hyperfast recovery
- ⑥ - Voltage rating (06 = 600 V)
- ⑦ -
  - None = TO-220AC
  - FP = TO-220 FULL-PAK
- ⑧ - Environmental digit:
  - PbF = lead (Pb)-free and RoHS-compliant
  - N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-8ETL06PbF	50	1000	Antistatic plastic tube
VS-8ETL06-N3	50	1000	Antistatic plastic tube
VS-8ETL06FPPbF	50	1000	Antistatic plastic tube
VS-8ETL06FP-N3	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions	TO-220AC	<a href="http://www.vishay.com/doc?95221">www.vishay.com/doc?95221</a>
	TO-220FP	<a href="http://www.vishay.com/doc?95005">www.vishay.com/doc?95005</a>
Part marking information	TO-220ACPbF	<a href="http://www.vishay.com/doc?95224">www.vishay.com/doc?95224</a>
	TO-220AC-N3	<a href="http://www.vishay.com/doc?95068">www.vishay.com/doc?95068</a>
	TO-220FPPbF	<a href="http://www.vishay.com/doc?95009">www.vishay.com/doc?95009</a>
	TO-220FP-N3	<a href="http://www.vishay.com/doc?95440">www.vishay.com/doc?95440</a>



**DIMENSIONS** in millimeters



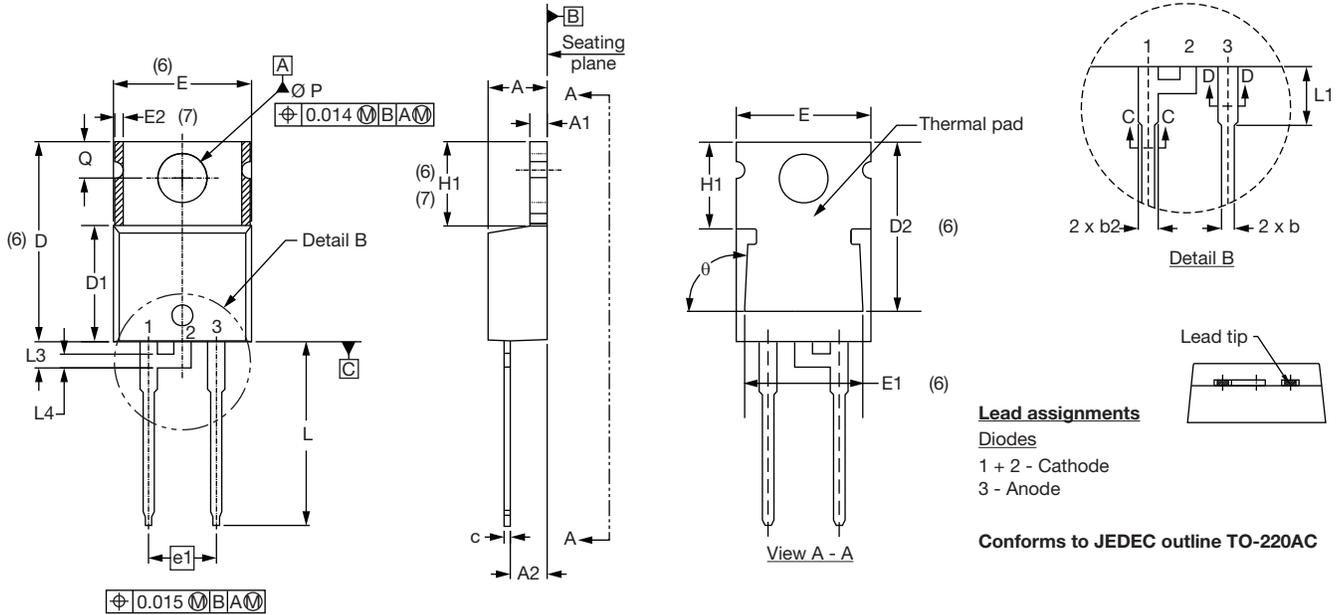
### Lead assignments

- Diodes
- 1 + 2 - Cathode
- 3 - Anode

Conforms to JEDEC outline TO-220 FULL-PAK

## TO-220AC

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183		E1	6.86	8.89	0.270	0.350	6
A1	1.14	1.40	0.045	0.055		E2	-	0.76	-	0.030	7
A2	2.56	2.92	0.101	0.115		e	2.41	2.67	0.095	0.105	
b	0.69	1.01	0.027	0.040		e1	4.88	5.28	0.192	0.208	
b1	0.38	0.97	0.015	0.038	4	H1	6.09	6.48	0.240	0.255	6, 7
b2	1.20	1.73	0.047	0.068		L	13.52	14.02	0.532	0.552	
b3	1.14	1.73	0.045	0.068	4	L1	3.32	3.82	0.131	0.150	2
c	0.36	0.61	0.014	0.024		L3	1.78	2.13	0.070	0.084	
c1	0.36	0.56	0.014	0.022	4	L4	0.76	1.27	0.030	0.050	2
D	14.85	15.25	0.585	0.600	3	Ø P	3.54	3.73	0.139	0.147	
D1	8.38	9.02	0.330	0.355		Q	2.60	3.00	0.102	0.118	
D2	11.68	12.88	0.460	0.507	6	θ	90° to 93°		90° to 93°		
E	10.11	10.51	0.398	0.414	3, 6						

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



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**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

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